## COMPONENT SIZE COMPARISON CHART **CHIP PACKAGES** SOD **POWER INDUCTORS** TRACK WIDTHS **HOLES ELECTROLYTIC CAPS** IMPERIAL JEDEC NAME JEDEC NAME BODY DIMENSIONS TRACK DIMENSIONS 0.1mm 3.0mm SOD-923 0.8x0.6x0.36 Size B 4.3x4.3 Bourns 0.56- 2.8-LPS4018 1000uH 0.125A 0.127mm SOT-923 ■ 0.6x0.8x0.50 0.127mm 01005 0.4x0.2 SOD-882 1.0x0.6x0.5 0.15mm Series 0.15mm 5.9 0201 SOT-723 1.2x0.8x0.50 0.6x0.3 0.2mm SOD-723 1.0x0.6x0.52 0.2mm 7.9 Differential 7.5x7.5 5 0mm 1.0x0.5 0.4mm SOT-563 1 2x1 6x0 55 SOD-523 1.2x0.8x0.6 Size C 5.3x5.3 0.5mm 19.7 0603 1.5x0.8 0.5mm 1 0mm 30.4 0805 2.0x1.3 SOD-323 1.7x1.3x1.0 SOT-363 2.15x1.3x1.0 inductor 0.8mm VIAs 1206 3.2x1.6 SOD-123 2 6v1 6v1 1 SOT-323 2.0x1.25x1.0 1.0mm ● HOLE DIA, COPPER DIA [mm] 10mm 1210 3.2x2.5 6.6x6.6 1.5mm • SOT-23-3 3.0x1.4x1.0 4.3x2.6x2.2 XTAL/OSC (DO-214AC) 0.2. 0.45 1.0. 2.0 1812 4.5x3.2 2.0mm 2.9x1.3x1.0 DIMENSIONS [mm] 0.3. 0.6 2010 4.3x3.6x2.2 5.0x2.5 (DO-214AA) 0.5. 1.0 8.3x8.3 Size F/F 2512 6.4x3.2 1.6x1.2x0.35 SOT-223 6.5x3.5x1.65 6 9x6 1x2 2 (DO-214AB) 2.0x1.6x0.55 CONNECTORS Terminal Block, P3.5, 5pos, RA 2725 2.5x2.0x0.55 Header (3) 1.27mm. 3.2x2.5x0.8 TH LEDs **MELF** 2x10 10.3x103 Size G Header, 7 4x5 NAME NAME DIMENSIONS [mm] 2920 2.0mm, 2x10 **®** HC-49/US 3mm (T1) MicroMELF 2 2x1 1 (H) (H) Header, 2.54mm. MiniMELE 3.5x1.5 (SOD-80) **TANTALUM CAPS** 5mm (T1-3/4) TH RESISTORS USB, Type A DIMENSIONS Imm MELE NAME 5.0x2.5 (DO-213) Size A 3.2x1.6x1.6 Horiz, 3x1.8 G-1111-0 Size B 3.5x2.8x1.9 SMA, Jack 10pos, With 0 P7.62 (1/8W) TH. Vert Leas 0 Horiz, 6.5x2.5 6.0x3.2x2.5 G-1111-0 Size C P10.16 (1/4W) Common 1.27mm 2x5 SMB, Jack Horiz, 8.5x3.2 Size D 7.3x4.3x2.8 Programming TH, Vert P15.24 (1/2W) Header 7.3x4.3x4.1 Size E P2.54 SMC Jack RA SMD W2B TH, Vert (S2B-PH-SM4 SOIC DIP **QFP QFN** BGA, WLP, CSP JEDEC NAME DIMENSIONS [mm] WLCSP-24 P0.5.10pos. SMD. Vert QFP-32, 5x5mm. 2.075x2.075mm RA. Back QFN-16, 3x3mm P0.4mm 3 Qv4 Qv1 5 SOIC-8N DIP-8 6.4x9.66x4.15 BGA-36, 3x3mm, P0.5mm QFN-56, 8x8mm QFP-32, 7x7mm, 5 275mm 5.275x5.4x2.2 BGA-96 wide (rare) 6x6mm, P0.5mm SOIC-16W 7.5x10.3x2.5 BGA-256 DIP-16 6 4x19 25x4 15 Transistor Outline (TO) P0.5mm TO-92 (TH) D2PAC (TO-263AA) (TO-252) **TSSOP** BGA-256 17x17mm, P1.0mm TSSOP-8 4.4x3.0x1.2 TO-220 (TH) mbedded.ninja TSSOP-16 4.4x5.0x1.2 v1.2.0 | 2023-08-13 | Scale 1:1 (A4) Where no nominal dimension was given, mid-point between min. and max. was used. Dimensions shown are body dimensions and do not include the leads. All views are topdown (hirds eve.) showing used PCB land area. Used land area will usually be slightly larger than shown due to copper pads extending past the edges of the leads. Packages have many synonyms, the names shown are based on popularity